

## 300mA CMOS LDO with Shutdown ERROR Output and Bypass

### Features

- Extremely Low Supply Current for Longer Battery Life
- Very Low Dropout Voltage
- 300mA Output Current
- Standard or Custom Output Voltages
- $\overline{\text{ERROR}}$  Output Can Be Used as a Low Battery Detector or Processor Reset Generator
- Power Saving Shutdown Mode
- Bypass Input for Ultra Quiet Operation
- Over Current and Over Temperature Protection
- Space-Saving MSOP Package Option

### Applications

- Battery Operated Systems
- Portable Computers
- Medical Instruments
- Instrumentation
- Cellular/GSM/PHS Phones
- Linear Post-Regulators for SMPS
- Pagers

### Device Selection Table

Part Number	Package	Junction Temp. Range
TC1173-xxVOA	8-Pin SOIC	-40°C to +125°C
TC1173-xxVUA	8-Pin MSOP	-40°C to +125°C

**NOTE:** xx indicates output voltages

Available Output Voltages: 2.5, 2.8, 3.0, 3.3, 5.0.

Other output voltages are available. Please contact Microchip Technology Inc. for details.

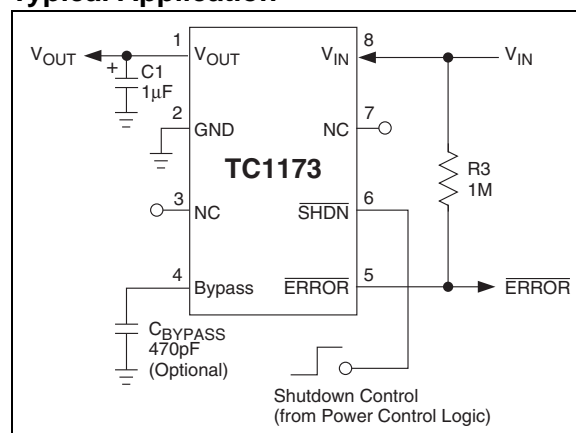
### General Description

The TC1173 is a precision output (typically  $\pm 0.5\%$ ) CMOS low dropout regulator. Total supply current is typically  $50\mu\text{A}$  at full load (20 to 60 times lower than in bipolar regulators).

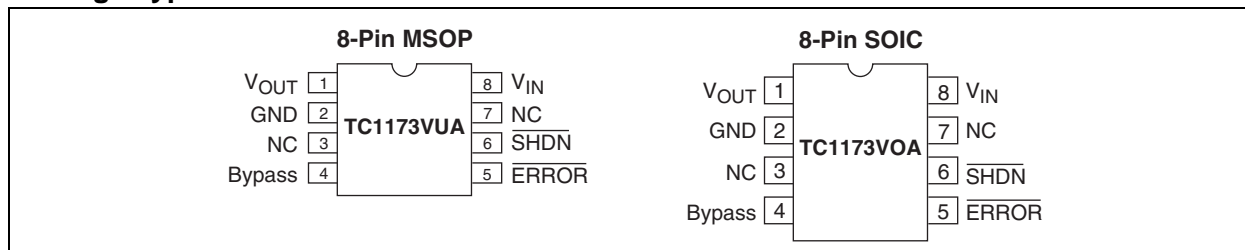
TC1173 key features include ultra low noise operation (plus optional Bypass input); very low dropout voltage (typically 240mV at full load) and internal feed-forward compensation for fast response to step changes in load. An error output ( $\overline{\text{ERROR}}$ ) is asserted when the TC1173 is out-of-regulation (due to a low input voltage or excessive output current).  $\overline{\text{ERROR}}$  can be set as a low battery warning or as a processor  $\overline{\text{RESET}}$  signal (with the addition of an external RC network). Supply current is reduced to  $0.05\mu\text{A}$  (typical) and  $V_{\text{OUT}}$  and  $\overline{\text{ERROR}}$  fall to zero when the shutdown input is low.

The TC1173 incorporates both over temperature and over current protection. The TC1173 is stable with an output capacitor of only  $1\mu\text{F}$  and has a maximum output current of 300mA.

### Typical Application



### Package Type



# TC1173

## 1.0 ELECTRICAL CHARACTERISTICS

### Absolute Maximum Ratings\*

Input Voltage .....	6.5V
Output Voltage.....	(V <sub>SS</sub> - 0.3V) to (V <sub>IN</sub> + 0.3V)
Power Dissipation.....	Internally Limited ( <b>Note 6</b> )
Maximum Voltage on Any Pin .....	V <sub>IN</sub> +0.3V to -0.3V
Operating Temperature Range.....	-40°C < T <sub>J</sub> < 125°C
Storage Temperature.....	-65°C to +150°C

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions above those indicated in the operation sections of the specifications is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

### TC1173 ELECTRICAL SPECIFICATIONS

**Electrical Characteristics:** V<sub>IN</sub> = V<sub>OUT</sub> + 1V, I<sub>L</sub> = 0.1mA, C<sub>L</sub> = 3.3μF,  $\overline{\text{SHDN}} > V_{IH}$ , T<sub>A</sub> = 25°C, unless otherwise noted. **Boldface** type specifications apply for junction temperatures of -40°C to +125°C.

Symbol	Parameter	Min	Typ	Max	Units	Test Conditions
V <sub>IN</sub>	Input Operating Voltage	<b>2.7</b>	—	<b>6.0</b>	V	<b>Note 8</b>
I <sub>OUTMAX</sub>	Maximum Output Current	<b>300</b>	—	—	mA	
V <sub>OUT</sub>	Output Voltage	— <b>V<sub>R</sub> - 2.5%</b>	V <sub>R</sub> ±0.5% —	— <b>V<sub>R</sub> + 2.5%</b>	V	<b>Note 1</b>
ΔV <sub>OUT</sub> /ΔT	V <sub>OUT</sub> Temperature Coefficient	—	<b>40</b>	—	ppm/°C	<b>Note 2</b>
ΔV <sub>OUT</sub> /ΔV <sub>IN</sub>	Line Regulation	—	0.05	<b>0.35</b>	%	(V <sub>R</sub> + 1V) ≤ V <sub>IN</sub> ≤ 6V
ΔV <sub>OUT</sub> /V <sub>OUT</sub>	Load Regulation	—	0.5	<b>2.0</b>	%	I <sub>L</sub> = 0.1mA to I <sub>OUTMAX</sub> ( <b>Note 3</b> )
V <sub>IN</sub> -V <sub>OUT</sub>	Dropout Voltage	—	20 80 240	<b>30</b> <b>160</b> <b>480</b>	mV	I <sub>L</sub> = 0.1mA I <sub>L</sub> = 100mA I <sub>L</sub> = 300mA ( <b>Note 4</b> )
I <sub>SS1</sub>	Supply Current	—	50	<b>90</b>	μA	$\overline{\text{SHDN}} = V_{IH}$
I <sub>SS2</sub>	Shutdown Supply Current	—	0.05	0.5	μA	$\overline{\text{SHDN}} = 0V$
PSRR	Power Supply Rejection Ratio	—	60	—	dB	F <sub>RE</sub> ≤ 1kHz
I <sub>OUTSC</sub>	Output Short Circuit Current	—	550	650	mA	V <sub>OUT</sub> = 0V
ΔV <sub>OUT</sub> /ΔP <sub>D</sub>	Thermal Regulation	—	0.04	—	V/W	<b>Note 5</b>
eN	Output Noise	—	260	—	nV/√Hz	F = 1kHz, C <sub>OUT</sub> = 1μF, R <sub>LOAD</sub> = 50Ω
<b>SHDN Input</b>						
V <sub>IH</sub>	$\overline{\text{SHDN}}$ Input High Threshold	<b>45</b>	—	—	%V <sub>IN</sub>	
V <sub>IL</sub>	$\overline{\text{SHDN}}$ Input Low Threshold	—	—	<b>15</b>	%V <sub>IN</sub>	
<b>ERROR Output</b>						
V <sub>MIN</sub>	Minimum Operating Voltage	1.0	—	—	V	
V <sub>OL</sub>	Output Logic Low Voltage	—	—	<b>400</b>	mV	1 mA Flows to $\overline{\text{ERROR}}$
V <sub>TH</sub>	$\overline{\text{ERROR}}$ Threshold Voltage	—	0.95 x V <sub>R</sub>	—	V	
V <sub>OL</sub>	$\overline{\text{ERROR}}$ Positive Hysteresis	—	50	—	mV	<b>Note 7</b>

**Note 1:** V<sub>R</sub> is the user-programmed regulator output voltage setting.

**Note 2:** TC V<sub>OUT</sub> =  $\frac{(V_{OUTMAX} - V_{OUTMIN}) \times 10^6}{V_{OUT} \times \Delta T}$

**Note 3:** Regulation is measured at a constant junction temperature using low duty cycle pulse testing. Load regulation is tested over a load range from 0.1mA to the maximum specified output current. Changes in output voltage due to heating effects are covered by the thermal regulation specification.

**Note 4:** Dropout voltage is defined as the input to output differential at which the output voltage drops 2% below its nominal value measured at a 1V differential.

**Note 5:** Thermal Regulation is defined as the change in output voltage at a time T after a change in power dissipation is applied, excluding load or line regulation effects. Specifications are for a current pulse equal to I<sub>LMAX</sub> at V<sub>IN</sub> = 6V for T = 10 msec.

**Note 6:** The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature and the thermal resistance from junction-to-air (i.e., T<sub>A</sub>, T<sub>J</sub>, θ<sub>JA</sub>). Exceeding the maximum allowable power dissipation causes the device to initiate thermal shutdown. Please see Section 4.0 Thermal Considerations for more details.

**Note 7:** Hysteresis voltage is referenced by V<sub>R</sub>.

**Note 8:** The minimum V<sub>IN</sub> has to justify the conditions: V<sub>IN</sub> ≥ V<sub>R</sub> + V<sub>DROPOUT</sub> and V<sub>IN</sub> ≥ 2.7V for I<sub>L</sub> = 0.1mA to I<sub>OUTMAX</sub>.

## 2.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 2-1.

**TABLE 2-1: PIN FUNCTION TABLE**

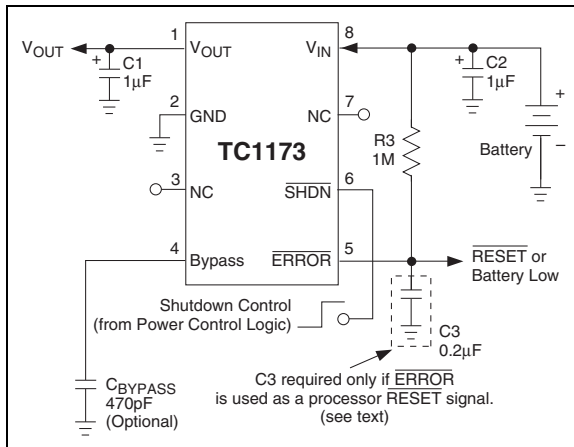
Pin No. (8-Pin SOIC) (8-Pin MSOP)	Symbol	Description
1	$V_{OUT}$	Regulated voltage output.
2	GND	Ground terminal.
3	NC	No connect.
4	Bypass	Reference bypass input. Connecting a 470pF to this input further reduces output noise.
5	$\overline{ERROR}$	Out-of-Regulation Flag. (Open drain output). This output goes low when $V_{OUT}$ is out-of-tolerance by approximately – 5%.
6	$\overline{SHDN}$	Shutdown control input. The regulator is fully enabled when a logic high is applied to this input. The regulator enters shutdown when a logic low is applied to this input. During shutdown, output voltage falls to zero and supply current is reduced to 0.05 $\mu$ A (typical).
7	NC	No connect.
8	$V_{IN}$	Unregulated supply input.

## 3.0 DETAILED DESCRIPTION

The TC1173 is a fixed output, low drop-out regulator. Unlike bipolar regulators, the TC1173's supply current does not increase with load current. In addition,  $V_{OUT}$  remains stable and within regulation over the entire 0mA to  $I_{OUTMAX}$  operating load current range, (an important consideration in RTC and CMOS RAM battery back-up applications).

Figure 3-1 shows a typical application circuit. The regulator is enabled any time the shutdown input ( $\overline{SHDN}$ ) is at or above  $V_{IH}$ , and shutdown (disabled) when  $\overline{SHDN}$  is at or below  $V_{IL}$ .  $\overline{SHDN}$  may be controlled by a CMOS logic gate, or I/O port of a microcontroller. If the  $\overline{SHDN}$  input is not required, it should be connected directly to the input supply. While in shutdown, supply current decreases to 0.05 $\mu$ A (typical),  $V_{OUT}$  falls to zero and  $\overline{ERROR}$  is disabled.

**FIGURE 3-1: TYPICAL APPLICATION CIRCUIT**



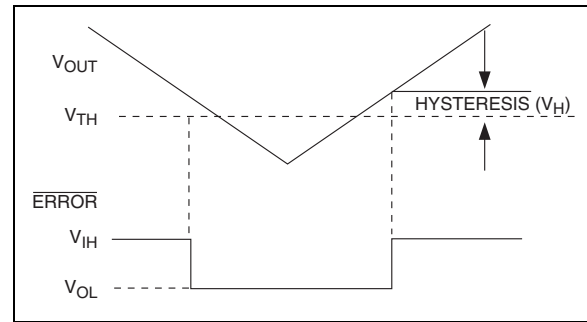
### 3.1 ERROR Output

$\overline{ERROR}$  is driven low whenever  $V_{OUT}$  falls out of regulation by more than  $-5\%$  (typical). This condition may be caused by low input voltage, output current limiting, or thermal limiting. The  $\overline{ERROR}$  threshold is 5% below rated  $V_{OUT}$  regardless of the programmed output voltage value (e.g.,  $\overline{ERROR} = V_{OL}$  at 4.75V (typ.) for a 5.0V regulator and 2.85V (typ.) for a 3.0V regulator).  $\overline{ERROR}$  output operation is shown in Figure 3-2.

Note that  $\overline{ERROR}$  is active when  $V_{OUT}$  is at or below  $V_{TH}$ , and inactive when  $V_{OUT}$  is above  $V_{TH} + V_H$ .

As shown in Figure 3-1,  $\overline{ERROR}$  can be used as a battery low flag, or as a processor  $\overline{RESET}$  signal (with the addition of timing capacitor C3).  $R1 \times C3$  should be chosen to maintain  $\overline{ERROR}$  below  $V_{IH}$  of the processor  $\overline{RESET}$  input for at least 200 msec to allow time for the system to stabilize. Pull-up resistor R1 can be tied to  $V_{OUT}$ ,  $V_{IN}$  or any other voltage less than  $(V_{IN} + 0.3V)$ .

**FIGURE 3-2: ERROR OUTPUT OPERATION**



### 3.2 Output Capacitor

A 1 $\mu$ F (min) capacitor from  $V_{OUT}$  to ground is recommended. The output capacitor should have an effective series resistance greater than 0.1 $\Omega$  and less than 5.0 $\Omega$ . A 1 $\mu$ F capacitor should be connected from  $V_{IN}$  to GND if there is more than 10 inches of wire between the regulator and the AC filter capacitor, or if a battery is used as the power source. Aluminum electrolytic or tantalum capacitor types can be used. (Since many aluminum electrolytic capacitors freeze at approximately  $-30^{\circ}\text{C}$ , solid tantalums are recommended for applications operating below  $-25^{\circ}\text{C}$ .) When operating from sources other than batteries, supply-noise rejection and transient response can be improved by increasing the value of the input and output capacitors and employing passive filtering techniques.

### 3.3 Bypass Input

A 470pF capacitor connected from the Bypass input to ground reduces noise present on the internal reference, which in turn significantly reduces output noise. If output noise is not a concern, this input may be left unconnected. Larger capacitor values may be used, but results in a longer time period to rated output voltage when power is initially applied.

## 4.0 THERMAL CONSIDERATIONS

### 4.1 Thermal Shutdown

Integrated thermal protection circuitry shuts the regulator off when die temperature exceeds 150°C. The regulator remains off until the die temperature drops to approximately 140°C.

### 4.2 Power Dissipation

The amount of power the regulator dissipates is primarily a function of input and output voltage, and output current. The following equation is used to calculate worst case actual power dissipation:

#### EQUATION 4-1:

$$P_D \approx (V_{INMAX} - V_{OUTMIN})I_{LOADMAX}$$

Where:

$P_D$  = Worst case actual power dissipation  
 $V_{INMAX}$  = Maximum voltage on  $V_{IN}$   
 $V_{OUTMIN}$  = Minimum regulator output voltage  
 $I_{LOADMAX}$  = Maximum output (load) current

The maximum allowable power dissipation (Equation 4-2) is a function of the maximum ambient temperature ( $T_{AMAX}$ ), the maximum allowable die temperature ( $T_{JMAX}$ ) and the thermal resistance from junction-to-air ( $\theta_{JA}$ ). The 8-Pin SOIC package has a  $\theta_{JA}$  of approximately 160°C/Watt, while the 8-Pin MSOP package has a  $\theta_{JA}$  of approximately 200°C/Watt.

#### EQUATION 4-2:

$$P_{DMAX} = \frac{(T_{JMAX} - T_{AMAX})}{\theta_{JA}}$$

Where all terms are previously defined.

Equation 4-1 can be used in conjunction with Equation 4-2 to ensure regulator thermal operation is within limits. For example:

Given:

$V_{INMAX} = 3.0V \pm 10\%$   
 $V_{OUTMIN} = 2.7V \pm 0.5\%$   
 $I_{LOADMAX} = 250mA$   
 $T_{JMAX} = 125^\circ C$   
 $T_{AMAX} = 55^\circ C$   
 $\theta_{JA} = 200^\circ C/W$   
 8-Pin MSOP Package

Find: 1. Actual power dissipation  
 2. Maximum allowable dissipation

Actual power dissipation:

$$\begin{aligned} P_D &\approx (V_{INMAX} - V_{OUTMIN})I_{LOADMAX} \\ &= [(3.0 \times 1.1) - (2.7 \times .995)]250 \times 10^{-3} \\ &= 155mW \end{aligned}$$

Maximum allowable power dissipation:

$$\begin{aligned} P_{DMAX} &= \frac{(T_{JMAX} - T_{AMAX})}{\theta_{JA}} \\ &= \frac{(125 - 55)}{200} \\ &= 350mW \end{aligned}$$

In this example, the TC1173 dissipates a maximum of 155mW; below the allowable limit of 350mW. In a similar manner, Equation 4-1 and Equation 4-2 can be used to calculate maximum current and/or input voltage limits. For example, the maximum allowable  $V_{IN}$  is found by substituting the maximum allowable power dissipation of 250mW into Equation 4-1, from which  $V_{INMAX} = 4.1V$ .

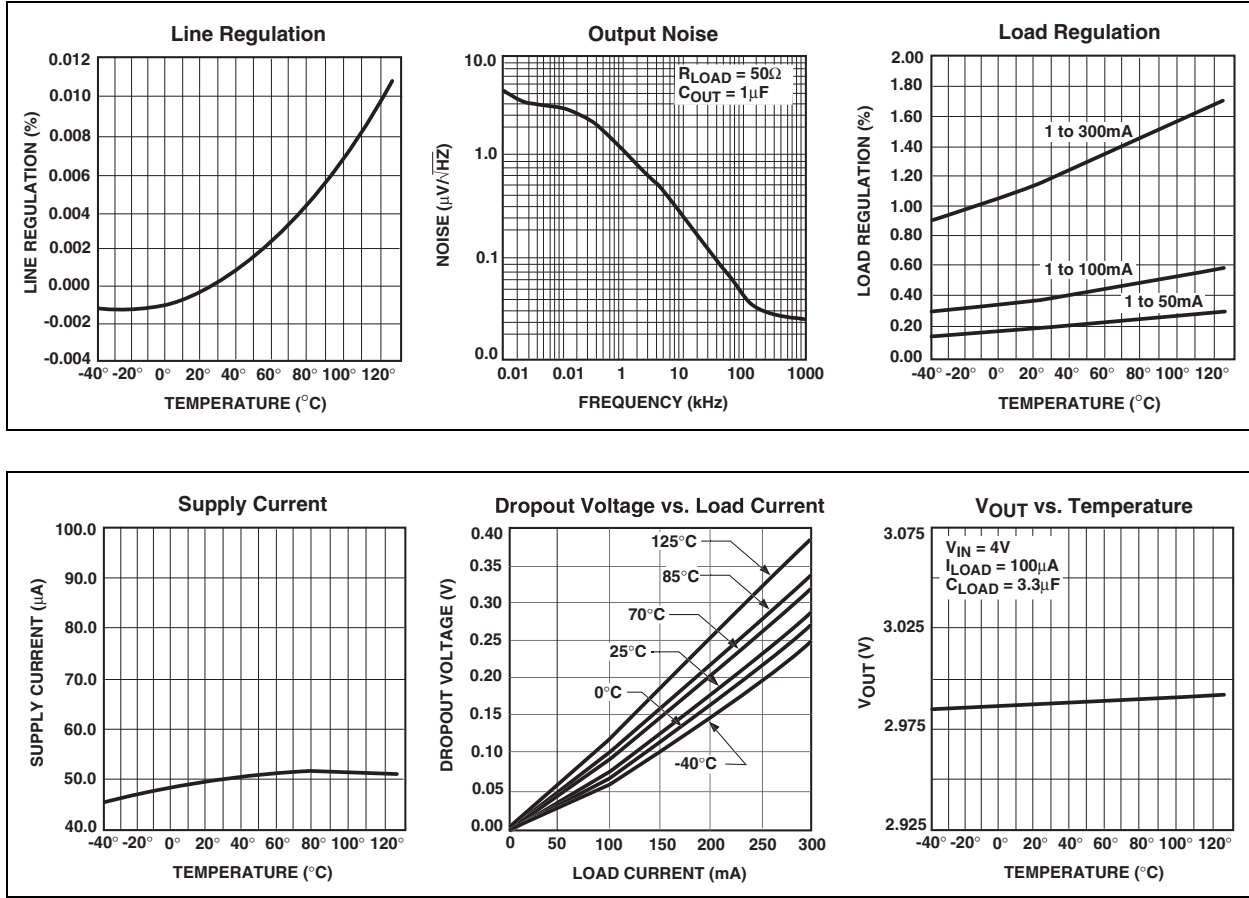
### 4.3 Layout Considerations

The primary path of heat conduction out of the package is via the package leads. Therefore, layouts having a ground plane, wide traces at the pads, and wide power supply bus lines combine to lower  $\theta_{JA}$  and therefore increase the maximum allowable power dissipation limit.

# TC1173

## 5.0 TYPICAL CHARACTERISTICS

**Note:** The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.



## 6.0 PACKAGING INFORMATION

### 6.1 Package Marking Information

Package marking data not available at this time.

### 6.2 Taping Form

**Component Taping Orientation for 8-Pin MSOP Devices**

Standard Reel Component Orientation  
for TR Suffix Device

Package	Carrier Width (W)	Pitch (P)	Part Per Full Reel	Reel Size
8-Pin MSOP	12 mm	8 mm	2500	13 in

**Component Taping Orientation for 8-Pin SOIC (Narrow) Devices**

Standard Reel Component Orientation  
for TR Suffix Device

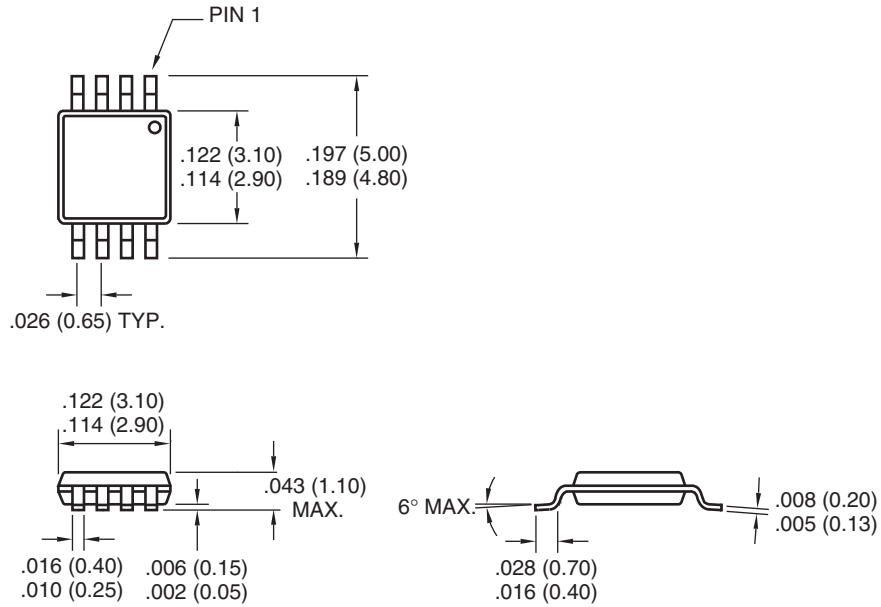
Package	Carrier Width (W)	Pitch (P)	Part Per Full Reel	Reel Size
8-Pin SOIC (N)	12 mm	8 mm	2500	13 in

# TC1173

## 6.3 Package Dimensions

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>

### 8-Pin MSOP

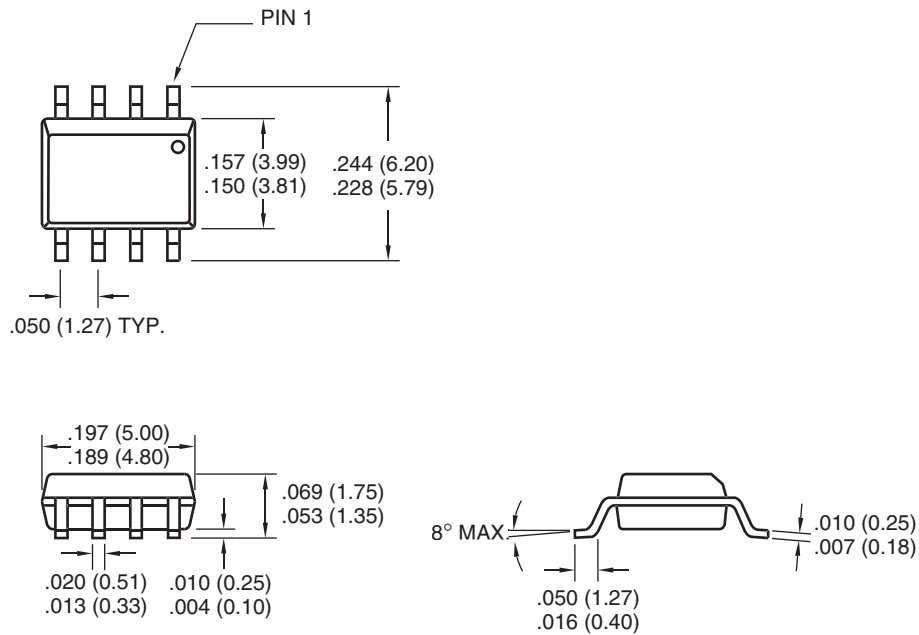


Dimensions: inches (mm)



**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>

## 8-Pin SOIC



Dimensions: inches (mm)

# TC1173

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## REVISION HISTORY

### Revision C (November 2012)

Added a note to each package outline drawing.

## SALES AND SUPPORT

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# TC1173

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NOTES:

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Tel: 82-2-554-7200  
Fax: 82-2-558-5932 or  
82-2-558-5934

**Malaysia - Kuala Lumpur**  
Tel: 60-3-6201-9857  
Fax: 60-3-6201-9859

**Malaysia - Penang**  
Tel: 60-4-227-8870  
Fax: 60-4-227-4068

**Philippines - Manila**  
Tel: 63-2-634-9065  
Fax: 63-2-634-9069

**Singapore**  
Tel: 65-6334-8870  
Fax: 65-6334-8850

**Taiwan - Hsin Chu**  
Tel: 886-3-5778-366  
Fax: 886-3-5770-955

**Taiwan - Kaohsiung**  
Tel: 886-7-213-7828  
Fax: 886-7-330-9305

**Taiwan - Taipei**  
Tel: 886-2-2508-8600  
Fax: 886-2-2508-0102

**Thailand - Bangkok**  
Tel: 66-2-694-1351  
Fax: 66-2-694-1350

### EUROPE

**Austria - Wels**  
Tel: 43-7242-2244-39  
Fax: 43-7242-2244-393

**Denmark - Copenhagen**  
Tel: 45-4450-2828  
Fax: 45-4485-2829

**France - Paris**  
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Fax: 33-1-69-30-90-79

**Germany - Munich**  
Tel: 49-89-627-144-0  
Fax: 49-89-627-144-44

**Italy - Milan**  
Tel: 39-0331-742611  
Fax: 39-0331-466781

**Netherlands - Drunen**  
Tel: 31-416-690399  
Fax: 31-416-690340

**Spain - Madrid**  
Tel: 34-91-708-08-90  
Fax: 34-91-708-08-91

**UK - Wokingham**  
Tel: 44-118-921-5869  
Fax: 44-118-921-5820

10/26/12



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



#### Как с нами связаться

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**Факс:** 8 (812) 320-02-42

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